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(54) **METHOD FOR MANUFACTURING
PHOTORESPONSIVE ARRAY ELEMENT**

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(71) Applicant: **CANON KABUSHIKI KAISHA,**
Tokyo (JP)

(72) Inventor: **TAKAYUKI TESHIMA,** Kanagawa
(JP)

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(57) **ABSTRACT**

A resist layer containing a photoresponsive material in a photoresist is layer-transferred from a film on which the resist layer is formed to a bank substrate, and exposure and development are performed so as to remove an unexposed resist layer.

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